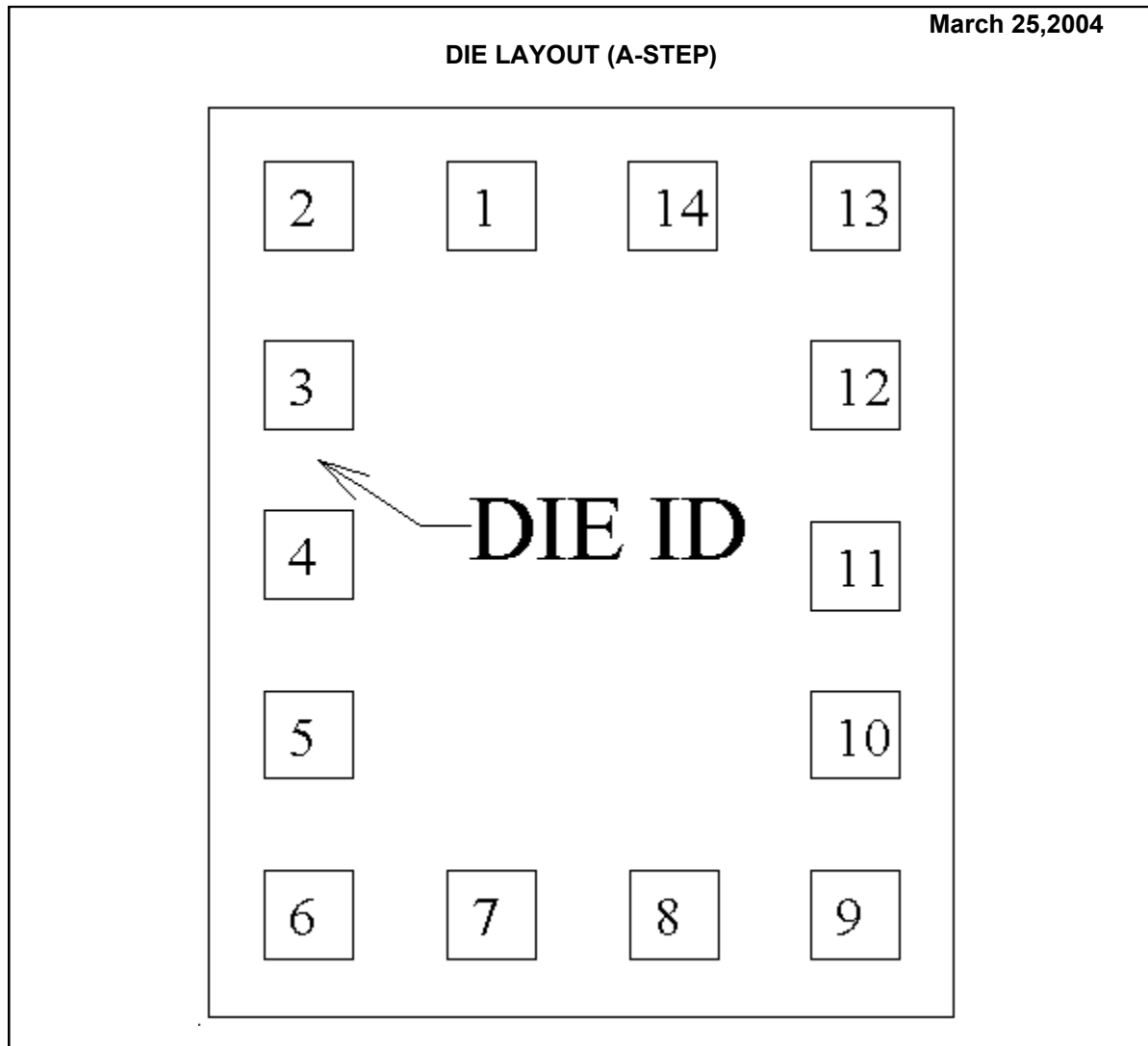


**LMV393 MDC MWC**  
**DUAL QUAD GENERAL PURPOSE, LOW VOLTAGE, COMPARATORS**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LMV393	Bond Pad Opening Size (min)	69µm x 69µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	584µm x 711µm 23.0mils x 28.0mils	Back Side Connection	Floating
Thickness	216µm Nominal		
Min Pitch	131µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
NC	1	-70	279	69	x	69
NC	2	-213	279	69	x	69
NC	3	-213	138	69	x	69
V+	4	-213	6	69	x	69
NC	5	-213	-135	69	x	69
NC	6	-213	-276	69	x	69
NC	7	-70	-276	69	x	69
OUTPUT A	8	73	-276	69	x	69
INPUT A -	9	215	-276	69	x	69
INPUT A+	10	215	-135	69	x	69
V -	11	215	-3	69	x	69
INPUT B+	12	215	138	69	x	69
INPUT B -	13	215	279	69	x	69
OUTPUT B	14	72	279	69	x	69

**LMV393 MDC MWC**  
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